



# IP4221CZ6-XS

ESD protection for high-speed interfaces

Rev. 2 — 13 December 2012

Product data sheet

## 1. Product profile

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### 1.1 General description

The device is designed to protect high-speed interfaces such as USB 2.0, Ethernet and Digital Visual Interface (DVI) against ElectroStatic Discharge (ESD).

The device includes four high-level ESD protection diode structures for high-speed signal lines and is encapsulated in a leadless ultra small DFN1010-6 (SOT891) plastic package.

Special diode configuration protects all signal lines and offers ultra low line capacitance of only 1 pF. The rail-to-rail diodes are connected to the Zener diode which allows ESD protection to be independent of supply voltage.

### 1.2 Features and benefits

- System ESD protection for high-speed data lines such as USB 2.0, Ethernet and DVI
- All signal lines with integrated rail-to-rail clamping diodes for downstream ESD protection of  $\pm 8$  kV according to IEC 61000-4-2, level 4
- Line capacitance of only 1 pF for each channel
- Leadless ultra small DFN1010-6 package:  $1 \times 1 \times 0.5$  mm; pitch 0.5 mm

### 1.3 Applications

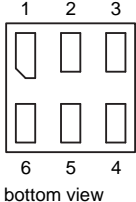
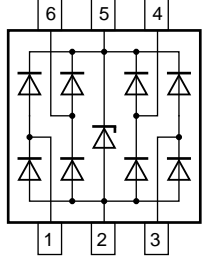
The device is designed for high-speed receiver and transmitter port protection:

- Mobile phones, smartphones and handsets
- TVs and monitors
- DVD recorders and players
- Notebooks, mother boards, graphic cards and ports
- Set-top boxes and game consoles



## 2. Pinning information

Table 1. Pinning

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	I/O 1	ESD protection	 <p>bottom view</p>	
2	GND	ground		
3	I/O 2	ESD protection		
4	I/O 3	ESD protection		
5	V <sub>CC</sub>	supply voltage		
6	I/O 4	ESD protection		

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## 3. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
IP4221CZ6-XS	DFN1010-6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891

## 4. Marking

Table 3. Marking codes

Type number	Marking code
IP4221CZ6-XS	1X

## 5. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>I</sub>	input voltage		-0.5	+5.5	V
V <sub>ESD</sub>	electrostatic discharge voltage	IEC 61000-4-2, level 4; <a href="#">[1]</a> contact discharge	-8	+8	kV
T <sub>stg</sub>	storage temperature		-55	+125	°C
T <sub>amb</sub>	ambient temperature		-40	+85	°C

[1] All pins to ground.

## 6. Characteristics

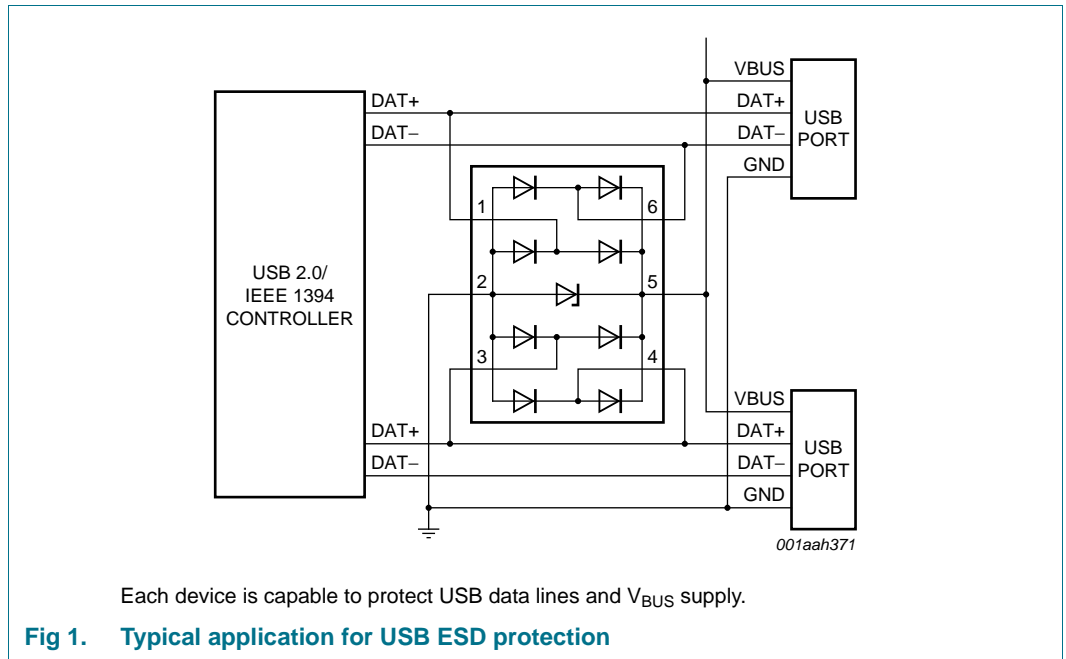
**Table 5. Characteristics**  
*T<sub>amb</sub> = 25 °C unless otherwise specified.*

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
C <sub>(I/O-GND)</sub>	input/output to ground capacitance	V <sub>I</sub> = 0 V; f = 1 MHz; V <sub>CC</sub> = 3 V	[1][2]	-	1	1.2 pF
I <sub>RM</sub>	reverse leakage current	V <sub>I</sub> = 3 V	[3][2]	-	100	nA
V <sub>BRzd</sub>	Zener diode breakdown voltage	I <sub>I</sub> = 1 mA	[4]	6	-	9 V
V <sub>F</sub>	forward voltage	I <sub>test</sub> = 10 mA	-	0.7	-	V

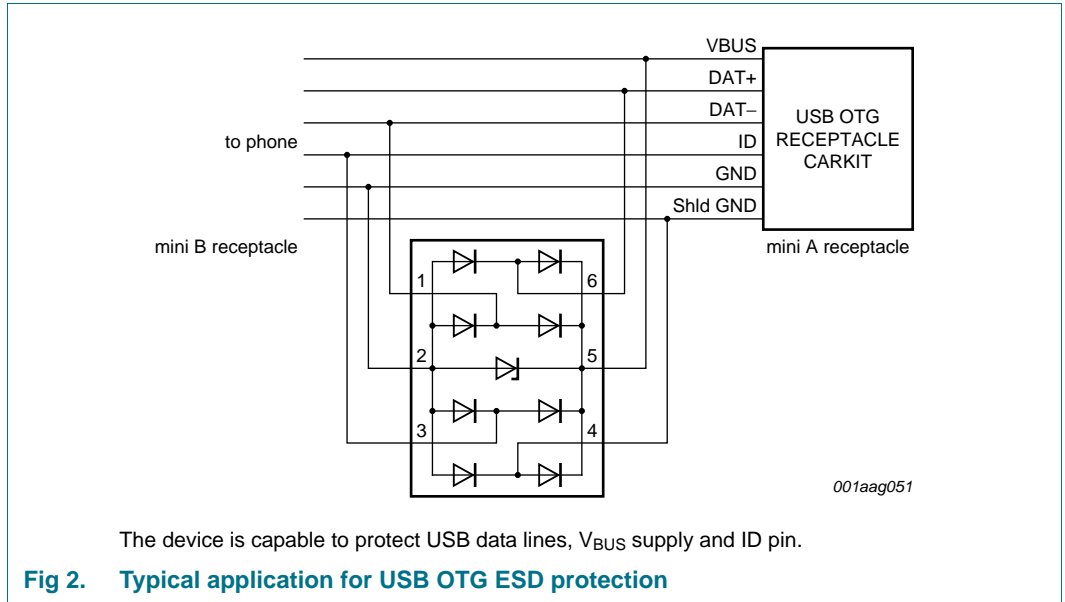
- [1] This parameter is guaranteed by design.
- [2] Pins 1, 3, 4 and 6 are measured to ground.
- [3] All pins measured to ground (pin 2).
- [4] Measured from pin 5 to pin 2.

## 7. Application information

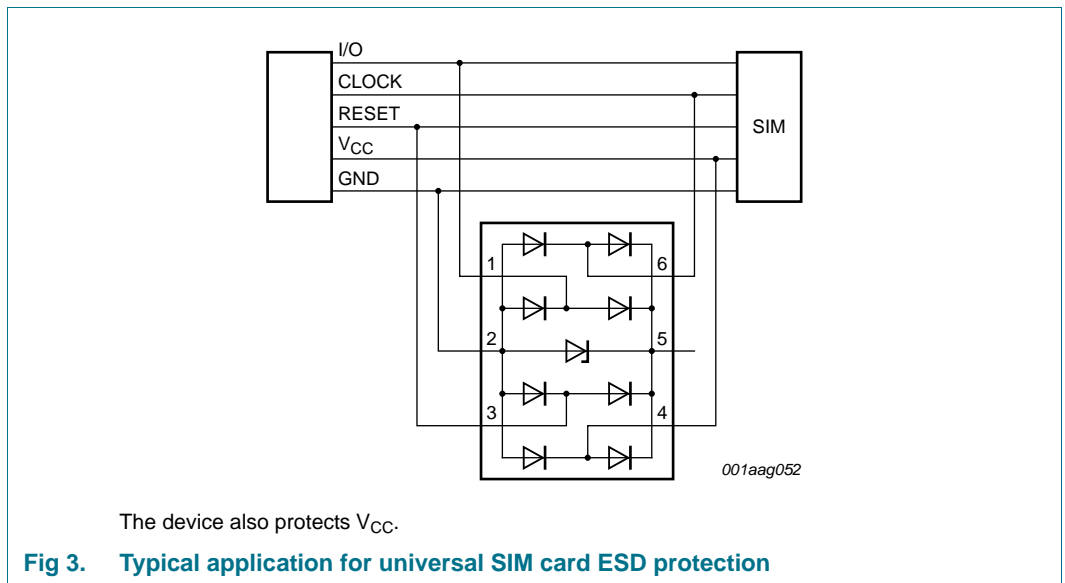
### 7.1 USB 1.1 and 2.0 protection



7.2 USB On-The-GO (OTG) protection



7.3 Universal SIM card protection



7.4 IEEE 1394a/b protection

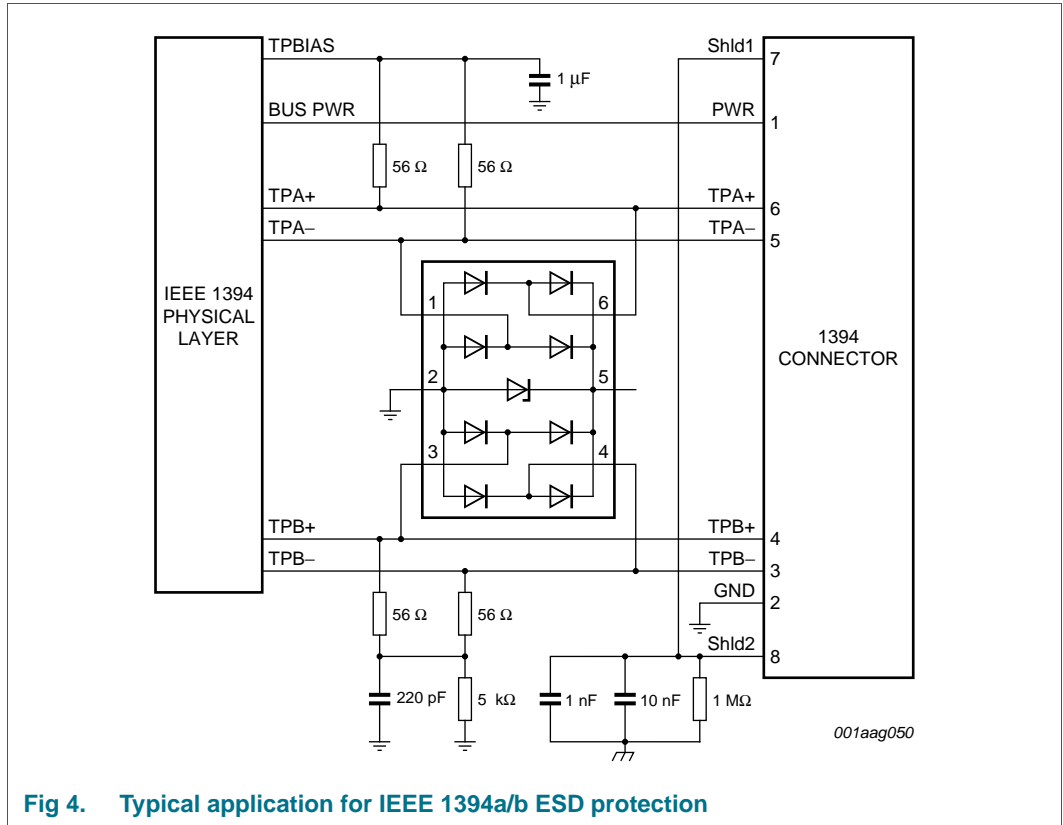


Fig 4. Typical application for IEEE 1394a/b ESD protection

7.5 Gigabit Ethernet transceiver protection

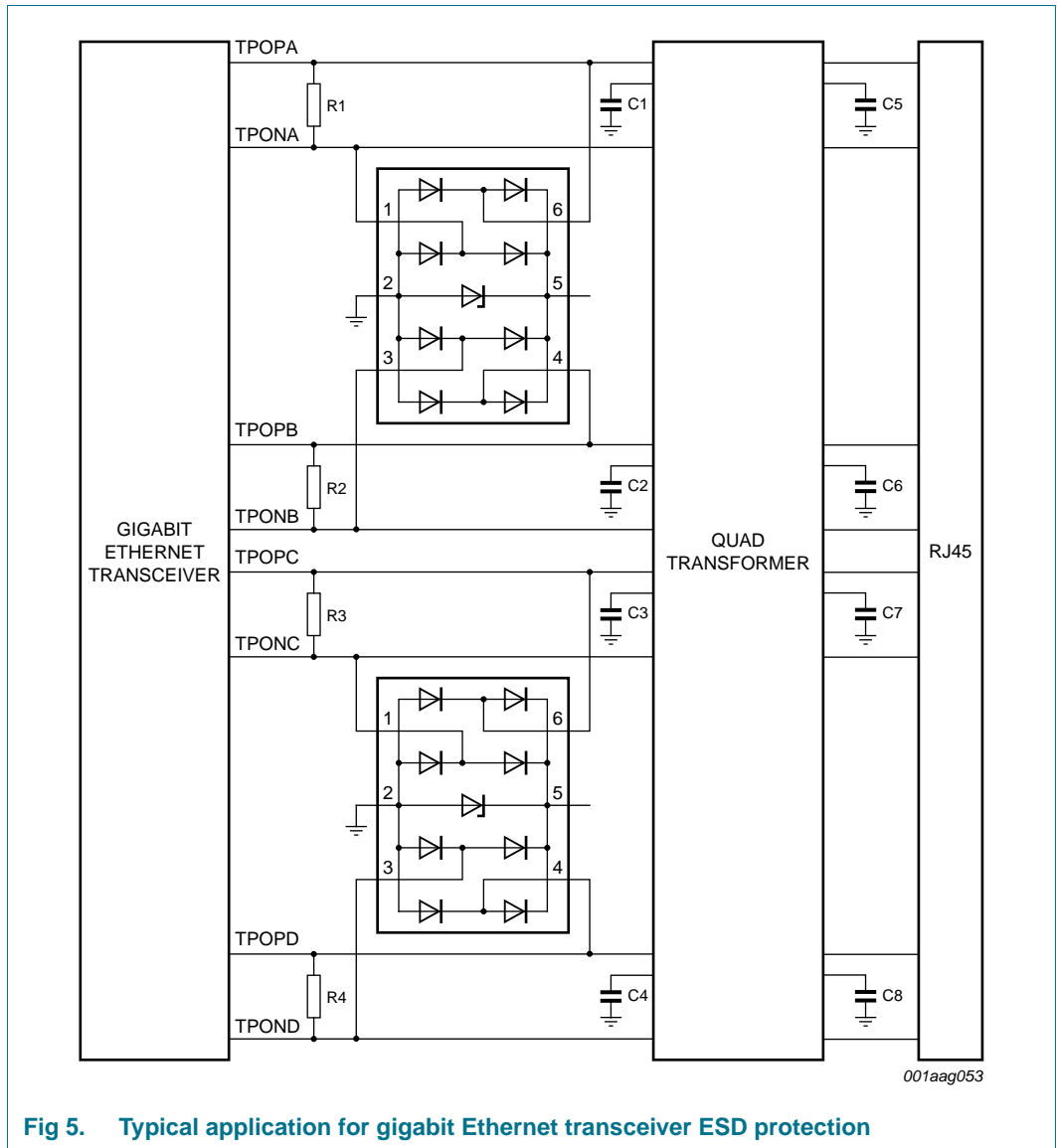


Fig 5. Typical application for gigabit Ethernet transceiver ESD protection

7.6 Universal microSD/TransFlash and SD memory card protection

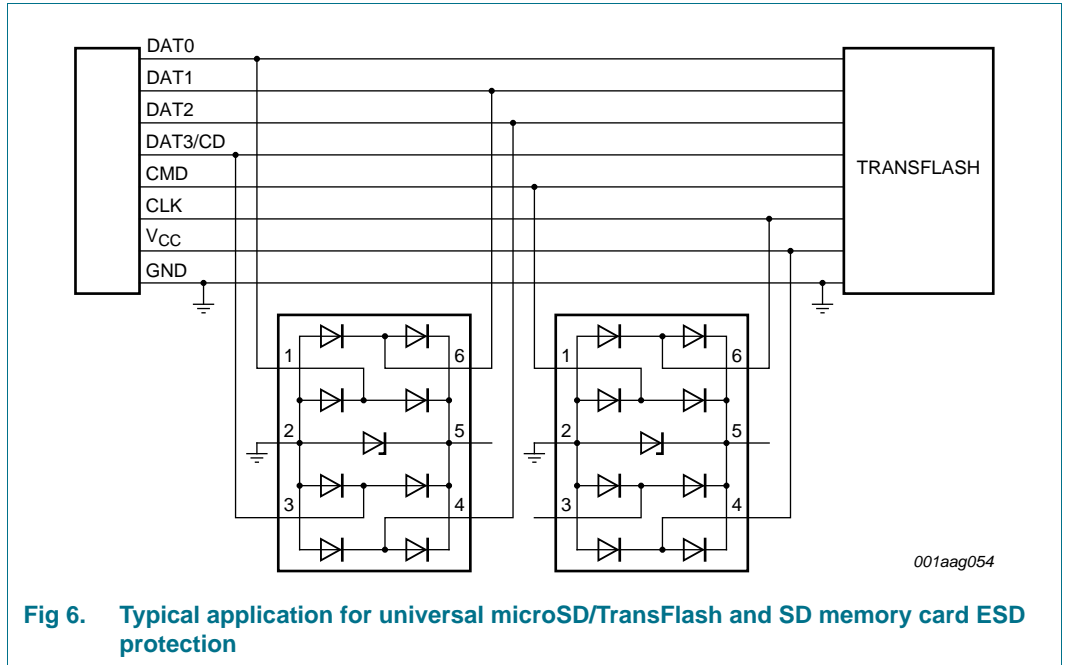


Fig 6. Typical application for universal microSD/TransFlash and SD memory card ESD protection

### 8. Package outline

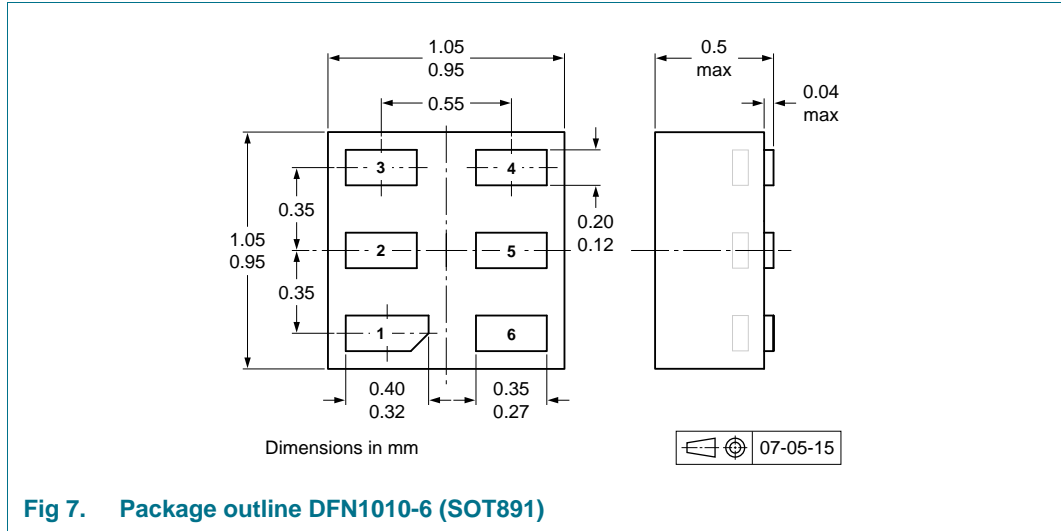


Fig 7. Package outline DFN1010-6 (SOT891)

### 9. Packing information

Table 6. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code. [1]

Type number	Package	Description	Packing quantity
			5000
IP4221CZ6-XS	DFN1010-6 (SOT891)	4 mm pitch, 8 mm tape and reel; T4	[2] -132

[1] For further information and the availability of packing methods, see Section 13.

[2] T4: reverse taping

### 10. Soldering

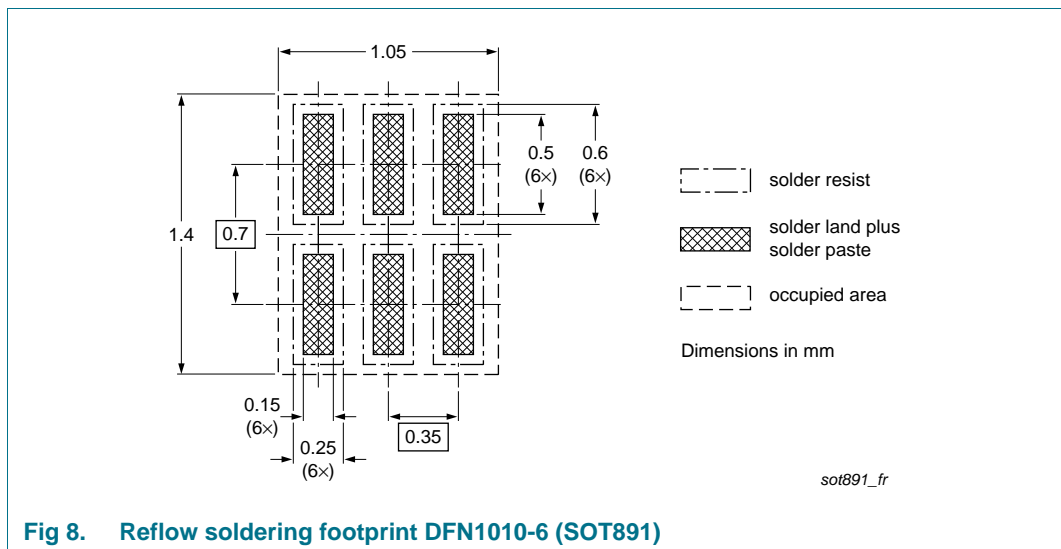


Fig 8. Reflow soldering footprint DFN1010-6 (SOT891)



## 11. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
IP4221CZ6-XS v.2	20121213	Product data sheet	-	IP4221CZ6-XS v.1
Modifications:	<ul style="list-style-type: none"> <li>• <a href="#">Section 1 "Product profile"</a>: updated</li> <li>• <a href="#">Section 4 "Marking"</a>: added</li> <li>• <a href="#">Section 5 "Limiting values"</a>: T<sub>amb</sub> added</li> <li>• Recommended operating conditions: removed</li> <li>• <a href="#">Table 5 "Characteristics"</a>: updated</li> <li>• <a href="#">Section 7 "Application information"</a>: updated</li> <li>• <a href="#">Section 8 "Package outline"</a>: drawing replaced with minimized package outline drawing</li> <li>• <a href="#">Section 10 "Soldering"</a>: added</li> <li>• <a href="#">Section 12 "Legal information"</a>: updated</li> </ul>			
IP4221CZ6-XS v.1	20070611	Objective data sheet	-	-

## 12. Legal information

### 12.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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